

Technical Data Sheet For Reference Only Thermally Conductive Epoxy

Date: September 2017 Recommended Cure: 80°C / 2 Hours

Rev: VI
No. of Components: Two
Mix Ratio by Weight: 100 : 14

Specific Gravity: Part A: 1.65 Part B: 0.96

Pot Life: 3 Hours

**Shelf Life- Bulk:** One year at room temperature

## NOTES:

• Container(s) should be kept closed when not in use.

- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.

<u>Product Description:</u> EPO-TEK® T905BN-3 is a thermally conductive, electrically insulating epoxy designed for heat sinking and encapsulation.

<u>Typical Properties:</u> Cure condition: 80°C / 2 Hours Different batches, conditions & applications yield differing results.

Data below is not guaranteed. To be used as a guide only, not as a specification. \* denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
* Color (before cure):		Part A: Grey	Part B: Clear
* Consistency:		Granular paste	
* Viscosity (23°C) @ 50 rpm:		2,000 - 7,000	cPs
Thixotropic Index:		1.5	
* Glass Transition Temp:		≥ 40	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)
Coefficient of Thermal Expansion	ı (CTE):		
Be	elow Tg:	37	x 10 <sup>-6</sup> in/in°C
Ab	oove Tg:	151	x 10 <sup>-6</sup> in/in°C
Shore D Hardness:		60	
Lap Shear @ 23°C:		> 1,600	psi
Die Shear @ 23°C:		≥ 10	Kg 3,556 psi
Degradation Temp:		347	°C
Weight Loss:			
@	200°C:	< 0.05	%
@	250°C:	0.16	%
@	300°C:	1.00	%
Suggested Operating Temperature:		< 300	°C (Intermittent)
Storage Modulus:		721,520	psi
* Particle Size:		≤ 300	microns

ELECTRICAL AND THERMAL PROPERTIES:					
Thermal Conductivity:	2.0	W/mK			
Volume Resistivity @ 23°C:	$\geq 3 \times 10^{11}$	Ohm-cm			
Dielectric Constant (1KHz):	3.51				
Dissipation Factor (1KHz):	0.009				



## **EPO-TEK® T905BN-3**

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## **EPO-TEK® T905BN-3 Advantages & Suggested Application Notes:**

- Potting applications:
  - o Low viscosity, self leveling epoxy is ideal for potting applications.
  - Low exothermic chemistry is ideal for large volume casting or potting up to 10 liters can be realized.
  - Reasonable pot-life allows for repeated cycles of vacuum and pressure, yielding bubble free epoxy and potted elements.
- High thermal conductivity allows for adhesive bonding of heat sinks and metal cases.
- Suggested applications:
  - Hybrids: staking and globbing high power SMDs to ceramic PCB
  - Medical: cooling of ultrasound and x-ray circuits, via adhesive and potting
  - Optical: thermally enhanced laser diode packaging
  - Electronics: encapsulating inductors, Cu coils and SMDs in transformer casings
- After cure, it is capable of being machined, grinded and polished into desired shapes.
- A grey color with a unique granular-like appearance. It should not be used above delicate Au wire bonds, resulting in sweep or break.